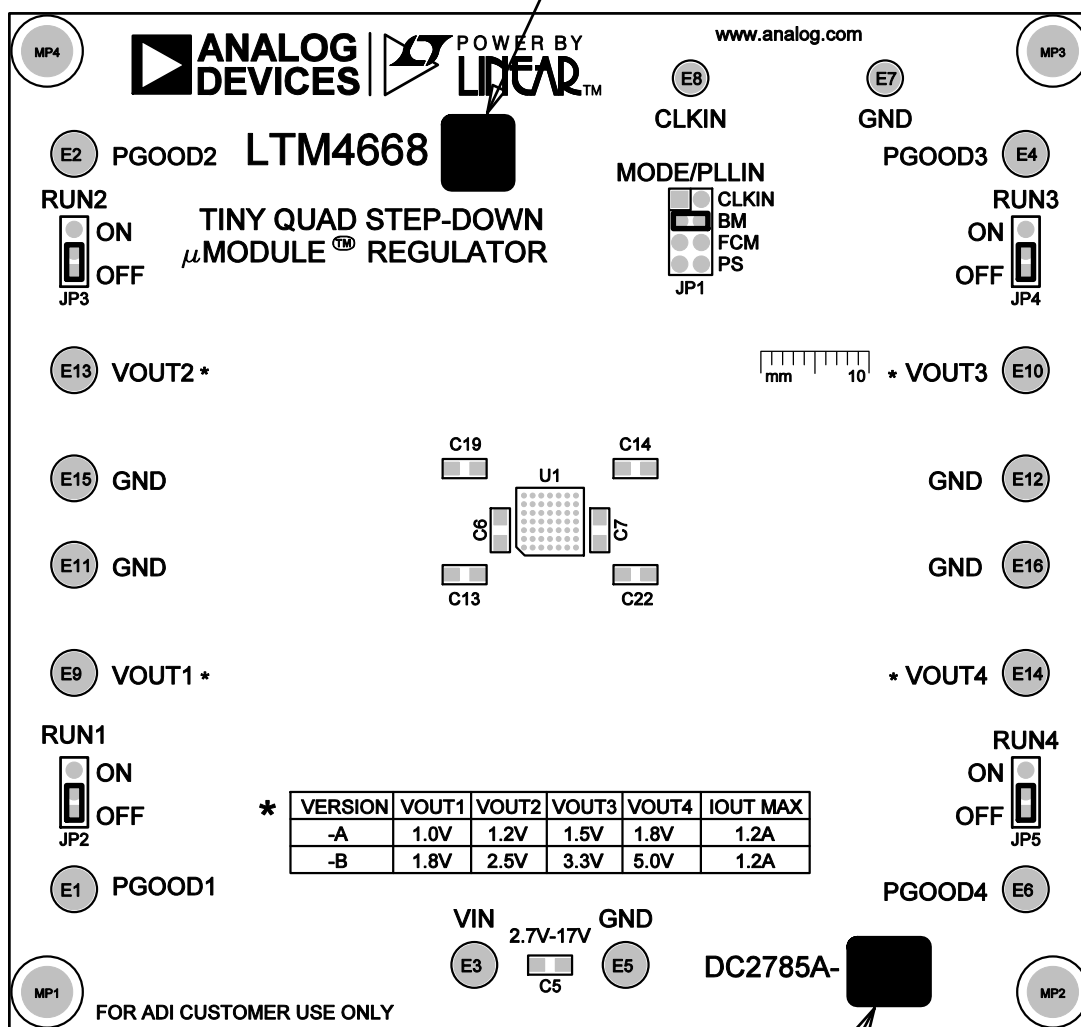


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS: REFLOW SOLDER TOP SIDE SMD.
MAXIMUM SOLDER TEMPERATURE IS 240 DEG. C.
3. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS WHERE SHOWN .
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP
TO ANY BOARD.
7. MARK ASSEMBLY VERSION WITH PERMANENT MARKER.



ANALOG DEVICES INC.

DC2785A REV 3
03/11/19

TOP SILKSCREEN
TOP ASSEMBLY

